IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Materi					rials and N	ials and Mfg Information			
upplier Infor	mation														
Company name*			Company unique ID			ι	Unique ID Authority					Response Date*			
onsemi											2025-0	2025-07-13			
Contact Name		Ti	Title - Contact			F	Phone - Contact*				Email ·	Email - Contact*			
Product-Env-Stev	wards	Pr	Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Repre	sentative*	Ti	Title - Representative			F	Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stev	wards	Product Enviro Compliance			1	NA				Produ	Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item Number Mf		Mfr Item Name			Effective Date	e Versio	on :	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP81239AMNTXG I2C configurable 4 switch bu adjustable output			4 switch buck/boos	st with	2025-07-13			PH1		74.24	mg	Each	
<b>I</b> anufacturing	g Proccess Informatio	n													
Terminal Plating / Grid Array Material T			Cerminal Base Alloy J-STD-020 MSI		-STD-020 MSL Ra	ating	Peak Process Body Temperature   Max Time at Pe		k Tempera	ture Num	ber of Reflow Cyc	cles			
Matte Tin (Sn) - annealed			CU Alloy 1				260	60 C 30		seconds 3					
omments	<u>-</u>						·					·			
vel 1 - maximum	ı time at peak temperature	during solder	ring is 10-30	seconds											
or more informa	tion regarding material co	mposition plea	ase refer to	page 3	·					·			·		

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.45	mg	Supplier	Silicon (Si)	7440-21-3		5.45	mg
Die Attach	0.94	mg	Supplier	Silver (Ag)	7440-22-4		0.799	mg
			Supplier	Acrylic resins	Proprietary Data		0.141	mg
Lead Frame	33.98	mg	Supplier	Silver (Ag)	7440-22-4		0.3398	mg
			Supplier	Tin (Sn)	7440-31-5		0.085	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0748	mg
			Supplier	Chromium (Cr)	7440-47-3		0.085	mg
			Supplier	Copper (Cu)	7440-50-8		33.3955	mg
Mold Compound-Black	32.07	mg		Epoxy resin	proprietary data		1.5073	mg
			Supplier	Phenol Resin	Proprietary Data		1.5073	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0321	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.0233	mg
Plating	1.58	mg	Supplier	Tin (Sn)	7440-31-5		1.58	mg
Wire Bond	0.22	mg	Supplier	Palladium (Pd)	7440-05-3		0.004	mg
			Supplier	Copper (Cu)	7440-50-8		0.216	mg